

Agenda for the Workshop “Wafer-scale Integration of 2D materials” 12th to 13th November 2019, Forum M Aachen

Tuesday 12 th November	
12:00-13:00	Welcome Reception (Lunch) Session Chair – Satender Kataria (RWTH)
13:00-13:10	Welcome and opening <i>Daniel Neumaier</i>
13:10-13:40	Electronic devices using TMDC's <i>Maximilian Pecht, Universität der Bundeswehr, München</i>
13:40-14:10	First steps of 2D material integration in 300mm silicon production line <i>Cedric Huyghebaert, IMEC, Belgium</i>
14:10-14:40	MOVPE of TMDC and 2D-2D Heterostructures <i>Holger Kalisch, RWTH Aachen University</i>
14:40-15:00	Front-End-of-Line integration of Graphene oxide and Biosensors <i>Vivek Pachauri, RWTH Aachen University</i>
15:00-16:00	Coffee Break + Poster Session Session Chair – Zhenxing Wang (AMO)
16:00-16:30	On the stacking and flipping of high-quality graphene-based heterostructures <i>Christoph Stampfer, RWTH Aachen University</i>
16:30-17:00	Process engineering for wafer-level integration of graphene into industrial applications <i>Sebastian Wittmann, Infineon Technologies, Regensburg</i>
17:00-17:20	Progress in large-scale transfer of graphene and 2D materials <i>Abhay Shivayogimath, DTU, Denmark</i>
17:20-17:50	Large-Area Integration of Two-Dimensional Materials and Their Heterostructures by Wafer Bonding <i>Arne Quellmalz, KTH Royal Institute of Technology, Sweden</i>
19:30-22:00	Dinner – Aachener Brauhaus Degraa (3-4min walking from the venue, see map attached)

Wednesday 13th November

Session Chair – Daniel Neumaier (AMO)

9:00-9:25	Graphene biosensors with CMOS readout <i>Sanna Arpiainen, VTT Technical Research Centre of Finland</i>
9:25-9:50	200 mm graphene growth and transfer for integration in microelectronics <i>Rasuole Lukose, IHP, Frankfurt (Oder)</i>
9:50-10:15	Wafer scale graphene processing – Progress at AMO <i>Zhenxing Wang, AMO GmbH, Aachen</i>
10:15-10:40	Graphene Integration Challenges <i>Amaia Zurutuza, Graphenea, Spain</i>
10:40-11:10	Coffee Break + Poster Session

Session Chair - Max Lemme (AMO/RWTH)

11:10-11:30	Graphene back-end-of-line integration requirements for image sensors <i>Stijn Goosens, ICFO, Spain</i>
11:30-12:00	GIMMIK: Graphene Technology on 200 mm Wafer for Microelectronic Applications <i>Michael Heuken, AIXTRON, Aachen</i>
12:00-12:30	CaF ₂ Insulators for Ultrascaled 2D Field Effect Transistors <i>Tibor Grasser, Tu Wien, Austria</i>
12:30-13:00	Monitoring of Graphene key control characteristics by THz wafer scanning systems <i>Michael Nagel, Protemics, Aachen</i>
13:00-14:00	Lunch
14:00-16:30	Tour at AIXTRON: Bus transfer from the venue is organized. Registration required.

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Route from the venue to the dinner:

